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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Min-Lung HUANG et al. Confirmation No: 8687
Appl. No. : 10/820,855
Filed : April 9, 2004
Title : Under Bump Metallization Structure Of A Semiconductor Wafer

TC/A.U. : 2814
Examiner : A. Kalam

Docket No.: : HUAN3262/REF
Customer No: : 23364

RESPONSE TO ELECTION REQUIREMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This is in response to the Official Action of May 8, 2007, in connection with the above identified application.


The Official Action is an election requirement in which it is urged that there are three separate and distinct species claimed in this application. It is further indicated that no claims are found to be generic. Applicant elects the species I, drawn to an under bump metallization structure comprising an adhesive layer formed on bonding pads, a first barrier layer disposed on the adhesive layer and a wetting layer formed on the first barrier layer without traverse. Claims 1-4, 6 and 7 are readable on the elected species. Applicants reserve the right to file one or more divisional applications on the non-elected inventions at a later time.

Appl. No. 10/820,855
Amendment dated: May 23, 2007
Reply to OA of: May 8, 2007

In view of the election of the species I, without traverse, an early and favorable action on the merits is now believed to be in order and is most respectfully requested.

Respectfully submitted,

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May 23, 2007